

# 2SD2046

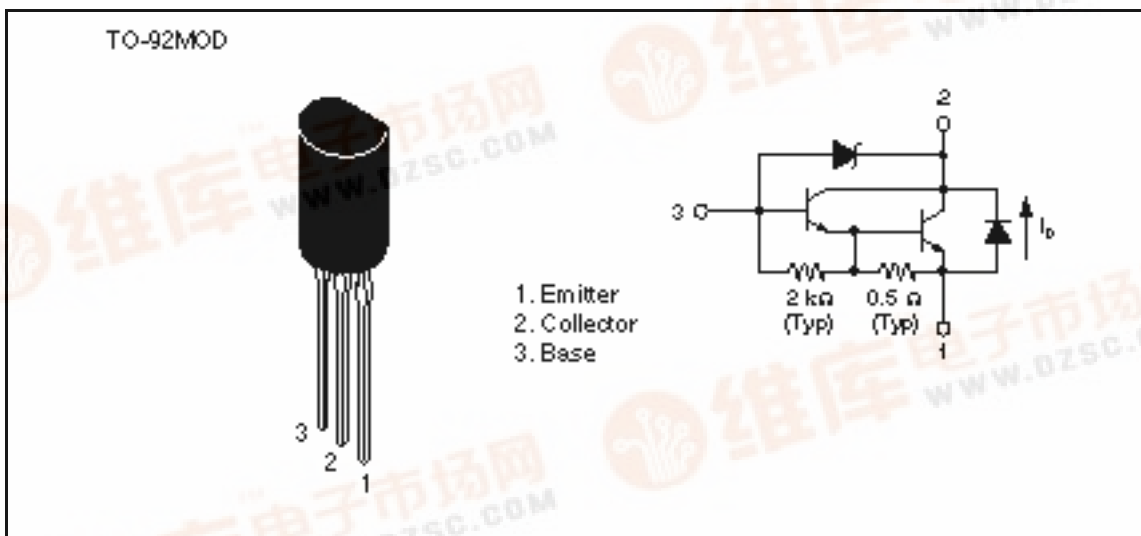
Silicon NPN Epitaxial, Darlington

# HITACHI

## Application

Low frequency power amplifier

## Outline



## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	50	V
Emitter to base voltage	$V_{EBO}$	7	V
Collector current	$I_C$	1.5	A
Collector peak current	$i_{c (peak)}$	3.0	A
Collector power dissipation	$P_C$	1.0	W
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C
E to C diode forward current	$I_D$	1.5	A

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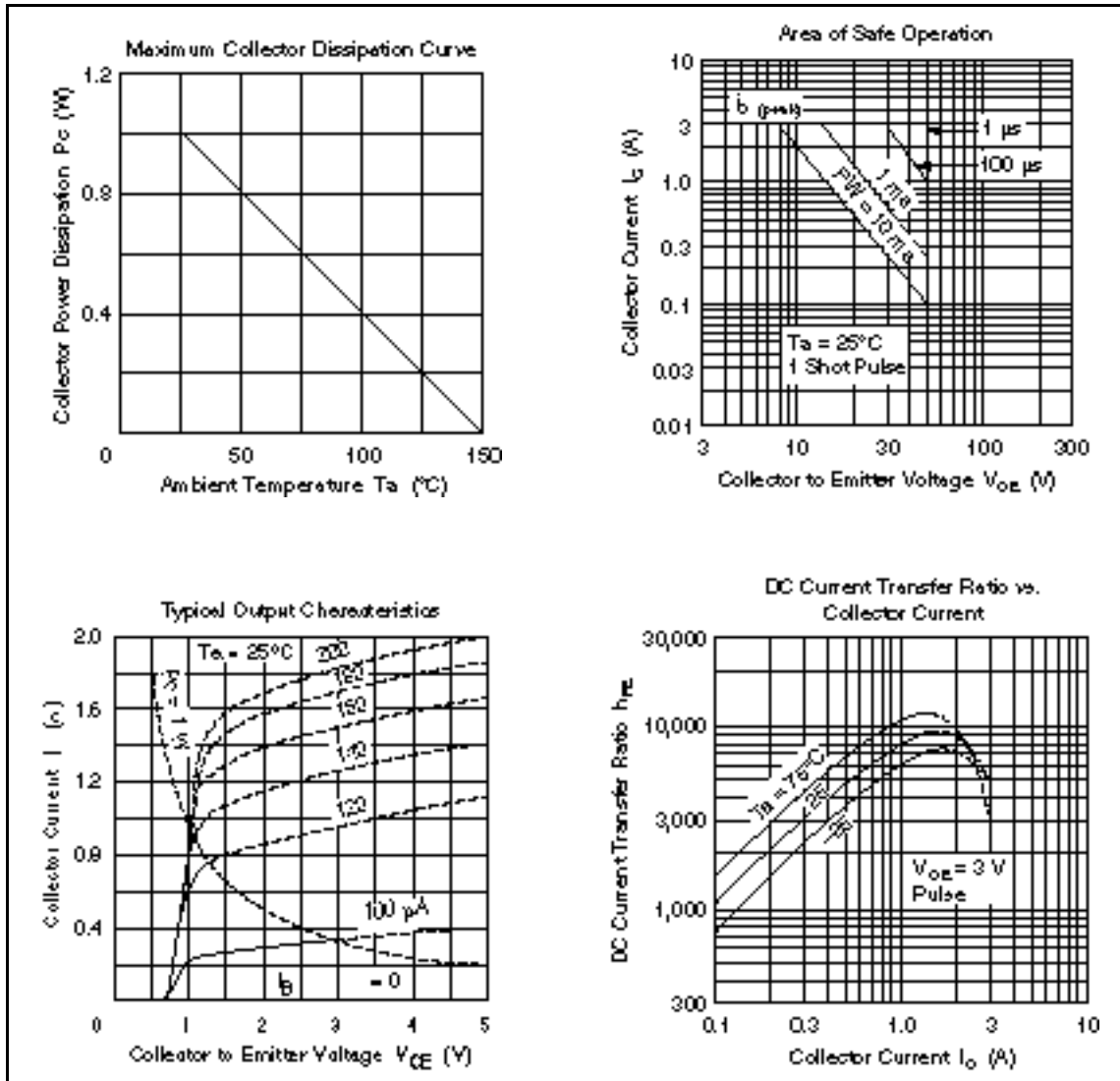
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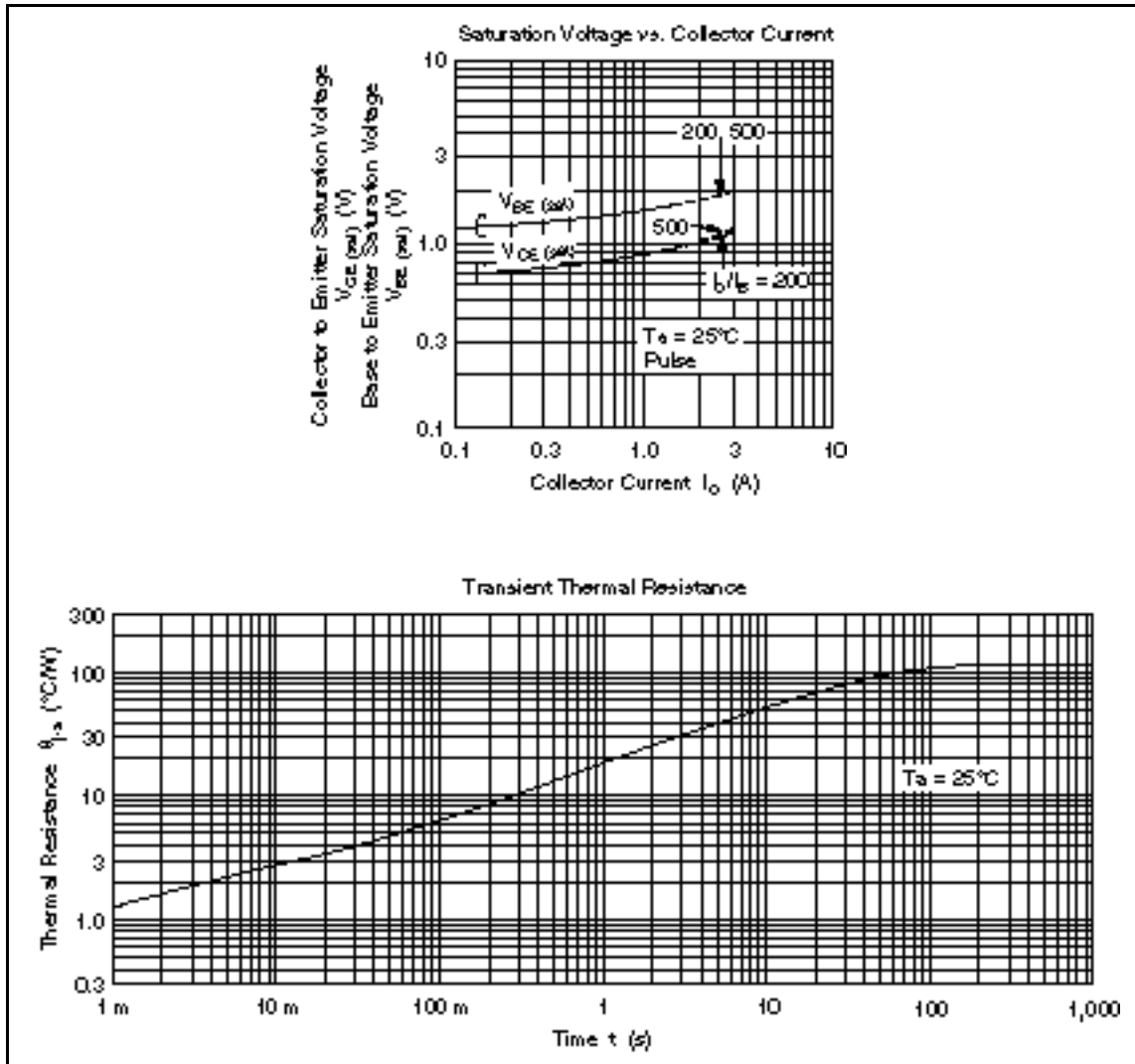
### Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage (Zener breakdown voltage)	$V_{(BR)CBO}$ ( $V_z$ )	50	60	70	V	$I_C = 0.1 \text{ mA}$ , $I_E =$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	—	—	V	$I_C = 10 \text{ mA}$ , $R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	—	—	V	$I_E = 50 \text{ mA}$ , $I_C = 0$
Collector cutoff current	$I_{CEO}$	—	—	10	$\mu\text{A}$	$V_{CE} = 40 \text{ V}$ , $R_{BE} =$
DC current transfer ratio	$h_{FE}$	2000	—	10000		$V_{CE} = 3 \text{ V}$ , $I_C = 1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{CE(sat)1}$	—	—	1.5	V	$I_C = 1 \text{ A}$ , $I_B = 1 \text{ mA}^{*1}$
	$V_{CE(sat)2}$	—	—	2.0	V	$I_C = 1.5 \text{ A}$ , $I_B = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	—	—	2.0	V	$I_C = 1 \text{ A}$ , $I_B = 1 \text{ mA}^{*1}$
	$V_{BE(sat)2}$	—	—	2.5	V	$I_C = 1.5 \text{ A}$ , $I_B = 1.5 \text{ mA}^{*1}$
E to C diode forward voltage	$V_D$	—	—	3.0	V	$I_D = 1.5 \text{ A}^{*1}$

Note: 1. Pulse test



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